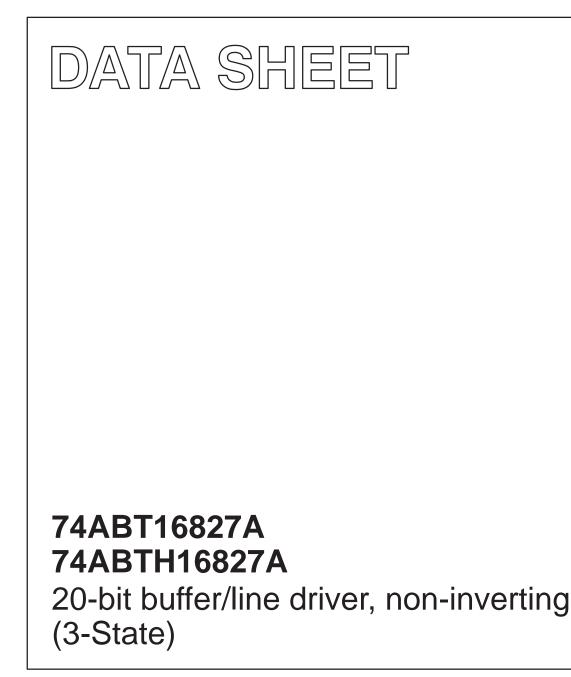
INTEGRATED CIRCUITS



Product specification Supersedes data of 1998 Feb 27 2002 Dec 17



74ABT16827A 74ABTH16827A

FEATURES

- Multiple V_{CC} and GND pins minimize switching noise
- Live insertion/extraction permitted
- 3-State output buffers
- Power-up 3-State
- 74ABTH16827A incorporates bus-hold data inputs which eliminate the need for external pull-up resistors to hold unused inputs
- Output capability: +64 mA / -32 mA
- Latch-up protection exceeds 500 mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model

DESCRIPTION

The 74ABT16827A high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT16827A 20-bit buffers provide high performance bus interface buffering for wide data/address paths or buses carrying parity. They have NOR Output Enables (n $\overline{OE1}$, n $\overline{OE2}$) for maximum control flexibility.

Two options are available, 74ABT16827A which does not have the bus-hold feature and 74ABTH16827A which incorporates the bus-hold feature.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25 °C; GND = 0 V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	$C_{L} = 50 \text{ pF}; \text{ V}_{CC} = 5 \text{ V}$	1.7 1.4	ns
C _{IN}	Input capacitance	$V_I = 0 V \text{ or } V_{CC}$	4	pF
C _{OUT}	Output capacitance	$V_{O} = 0 V \text{ or } V_{CC}$; 3-State	6	pF
I _{CCZ}	Quiescent supply current	Outputs disabled; V_{CC} = 5.5 V	500	μΑ
ICCL		Outputs LOW; $V_{CC} = 5.5 V$	9	mA

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	PART NUMBER	DWG NUMBER
56-Pin Plastic SSOP Type III	–40 °C to +85 °C	74ABT16827ADL	SOT371-1
56-Pin Plastic TSSOP Type II	–40 °C to +85 °C	74ABT16827ADGG	SOT364-1
56-Pin Plastic TSSOP Type II	–40 °C to +85 °C	74ABTH16827ADGG	SOT364-1

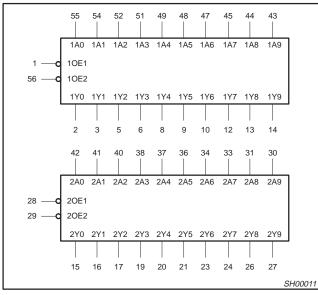
PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
55, 54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31, 30	1A0 – 1A9 2A0 – 2A9	Data inputs
2, 3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26, 27	1Y0 – 1Y9 2Y0 – 2Y9	Data outputs
1, 56, 28, 29	10E0, 10E1 20E0, 20E1	Output enable inputs (active-LOW)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0 V)
7, 22, 35, 50	V _{CC}	Positive supply voltage

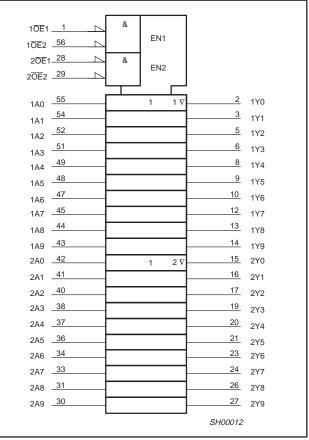
74ABT16827A 74ABTH16827A

PIN CONFIGURATION 1<u>0E</u>2 1<u>0</u>E1 1 56 1Y0 2 55 1A0 1Y1 54 1A1 3 53 GND 4 GND 1Y2 5 52 1A2 1Y3 6 51 1A3 7 50 Vcc Vcc 49 8 1Y4 1A4 48 9 1A5 1Y5 1Y6 10 47 1A6 11 46 GND GND 1Y7 12 45 1A7 44 1Y8 13 1A8 43 1Y9 14 1A9 42 2Y0 15 2A0 41 2A1 2Y1 16 2Y2 17 40 2A2 GND 18 39 GND 19 38 2A3 2Y3 2Y4 20 37 2A4 21 36 2A5 2Y5 35 V_{CC} 22 V_{CC} 2Y6 23 34 2A6 24 33 2A7 2Y7 GND 25 32 GND 2A8 2Y8 26 31 2Y9 27 30 2A9 20E1 28 29 20E2 SH00010

LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

INPU	JTS	OUTPUTS	OPERATING MODE
nOEx	nAx	nYx	
L	L	L	Transparent
L	Н	Н	Transparent
Н	Х	Z	High impedance
V D-	- 14		

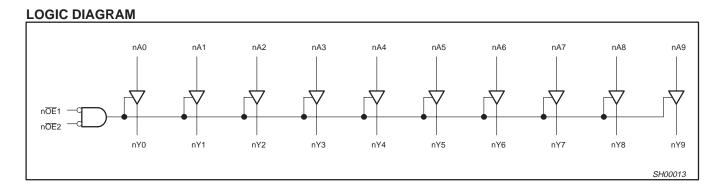
X = Don't care

Z = High impedance "off" state

H = HIGH voltage level

L = LOW voltage level

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ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER CONDITIONS		RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V _I < 0 V	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{ОК}	DC output diode current	V _O < 0 V	-50	mA
V _{OUT}	DC output voltage ³	Output in Off or HIGH state	-0.5 to +5.5	V
		Output in LOW state	128	mA
IOUT	DC output current	Output in HIGH state	-64	mA
T _{stg}	Storage temperature range		–65 to 150	°C

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

3.

RECOMMENDED OPERATING CONDITIONS

SYMBOL			LIMITS		
STWBOL	PARAMETER	MIN	MAX	UNIT	
V _{CC}	DC supply voltage	4.5	5.5	V	
VI	Input voltage	0	V _{CC}	V	
V _{IH}	HIGH-level input voltage	2.0	-	V	
V _{IL}	LOW-level Input voltage	-	0.8	V	
I _{ОН}	H HIGH-level output current –		-32	mA	
I _{OL}	L LOW-level output current – 64		64	mA	
Δt/Δv	Input transition rise or fall rate	0	10	ns/V	
T _{amb}	Operating free-air temperature range	-40	+85	°C	

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DC ELECTRICAL CHARACTERISTICS

					LIMITS				
SYMBOL	PARAMETER	TEST CONDITIONS	6	T _{amb} = +25 °C			T _{amb} = −40 °C to +85 °C		UNIT
				MIN	TYP	MAX	MIN	MAX	1
VIK	Input clamp voltage	V _{CC} = 4.5 V; I _{IK} = -18 mA			-0.9	-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V}; I_{OH} = -3 \text{ mA}; V_I = V$	IL or VIH	2.5	2.9		2.5		V
V _{OH}	HIGH-level output voltage	$V_{CC} = 5.0 \text{ V}; \text{ I}_{OH} = -3 \text{ mA}; \text{ V}_{I} = \text{ V}$	IL or VIH	3.0	3.4		3.0		V
		V_{CC} = 4.5 V; I_{OH} = -32 mA; V_{I} =	V _{IL} or V _{IH}	2.0	2.4		2.0		V
V _{OL}	LOW-level output voltage	$V_{CC} = 4.5 \text{ V}; I_{OL} = 64 \text{ mA}; V_I = V$	_{IL} or V _{IH}		0.42	0.55		0.55	V
Ц	Input leakage current	V_{CC} = 5.5 V; V_{I} = GND or 5.5 V			±0.01	±1.0		±1.0	μΑ
		$V_{CC} = 5.5 \text{ V}; \text{ V}_{I} = 5.5 \text{ V}$			0.01	1		1	μΑ
ь.	Input leakage current	V_{CC} = 5.5 V; V_{I} = V_{CC} or GND	Control pins		±0.01	±1		±1	μΑ
łı	74ABTH16827A	$V_{CC} = 5.5 \text{ V}; \text{ V}_{I} = V_{CC}$	Data sise4		0.01	1		1	μΑ
	$V_{CC} = 5.5 \text{ V}; \text{ V}_1 = 0$ Data pins ⁴			-1	-3		-5	μΑ	
		$V_{CC} = 4.5 \text{ V}; V_{I} = 0.8 \text{ V}$ $V_{CC} = 4.5 \text{ V}; V_{I} = 2.0 \text{ V}$		35			35		
I _{HOLD}	Bus Hold current A inputs ⁵ 74ABTH16827A			-75			-75		μA
		$V_{CC} = 5.5 \text{ V}; \text{ V}_{I} = 0 \text{ to } 5.5 \text{ V}$		±800					
I _{OFF}	Power-off leakage current	$V_{CC} = 0.0 \text{ V}; V_{O} = 4.5 \text{ V}; V_{I} = 0 \text{ V}$	/ or 5.5 V		±5.0	±100		±100	μΑ
I _{PU} /I _{PD}	Power-up/down 3-State output current ³	V_{CC} = 2.1 V; V_{O} = 0.5 V; V_{I} = GND or V_{CC} ; V_{OE} = Don't care			±5.0	±50		±50	μA
I _{OZH}	3-State output High current	$V_{CC} = 5.5 \text{ V}; V_{O} = 2.7 \text{ V}; V_{I} = V_{IL} \text{ or } V_{IH}$			1.0	10		10	μΑ
I _{OZL}	3-State output Low current	$V_{CC} = 5.5 \text{ V}; V_{O} = 0.5 \text{ V}; V_{I} = V_{IL} \text{ or } V_{IH}$			-1.0	-10		-10	μΑ
I _{CEX}	Output HIGH leakage current	V_{CC} = 5.5 V; V_{O} = 5.5 V; V_{I} = GND or V_{CC}			1.0	50		50	μA
Ι _Ο	Output current ¹	V _{CC} = 5.5 V; V _O = 2.5 V		-50	-70	-180	-50	-180	mA
I _{CCH}		V_{CC} = 5.5 V; Outputs HIGH, V _I = GND or V _{CC}			0.5	1		1	mA
I _{CCL}	Quiescent supply current	V_{CC} = 5.5 V; Outputs LOW, V _I = GND or V _{CC}			9	19		19	mA
I _{CCZ}		V_{CC} = 5.5 V; Outputs 3-State; V _I = GND or V _{CC}	V _{CC} = 5.5 V; Outputs 3-State;		0.5	1		1	mA
ΔI_{CC}	Additional supply current per input pin ²	V_{CC} = 5.5 V; one input at 3.4 V, other inputs at V _{CC} or GND			0.2	1		1	mA

NOTES:

1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input at 3.4 V.
This parameter is valid for any V_{CC} between 0 V and 2.1 V with a transition time of up to 10 msec. From V_{CC} = 2.1 V to V_{CC} = 5 V ± 10% a transition time of up to 100 μsec is permitted.
Unused pins at V_{CC} or GND.
This is the bus hold overdrive current required to force the input to the opposite logic state.

AC CHARACTERISTICS

GND = 0 V, $t_R = t_F = 2.5$ ns, $C_L = 50$ pF, $R_L = 500$ Ω

				LIMITS				
SYMBOL	PARAMETER	WAVEFORM	T, V	amb = +25 ° / _{CC} = +5.0	°C V	T _{amb} = -40 V _{CC} = +5.	°C to +85 °C 0 V ±0.5 V	UNIT
			MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	1	1.0 0.6	1.7 1.4	2.4 2.0	1.0 0.6	2.7 2.3	ns
t _{PZH} t _{PZL}	Output enable time to HIGH and LOW level	2	1.0 1.0	3.0 3.0	4.1 4.0	1.0 1.0	5.0 5.0	ns
t _{PHZ} t _{PLZ}	Output disable time 2 from HIGH and LOW level		2.0 1.6	3.2 2.4	4.3 3.2	2.0 1.6	5.0 3.5	ns

3.5V

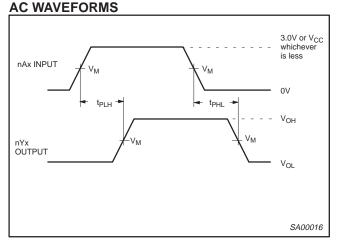
V_{OL} + 0.3V

20-bit buffer/line driver, non-inverting (3-State)

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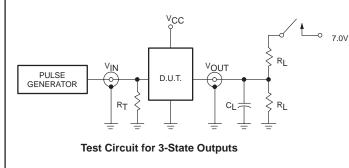
٧м

^tPLZ ⁻



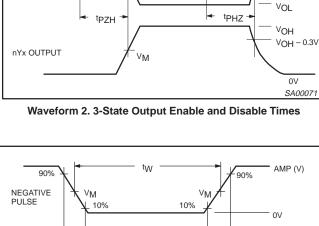
Waveform 1. Input (nAx) to Output (nYx) Propagation Delays

TEST CIRCUIT AND WAVEFORM



SWITCH POSITION

TEST	SWITCH
t _{PLZ}	closed
t _{PZL}	closed
All other	open



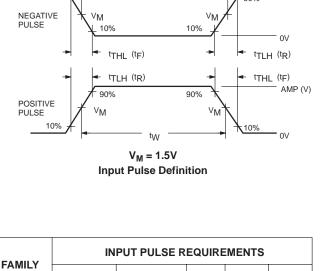
M

nOEx INPUT

nYx OUTPUT

٧M

^tPZL

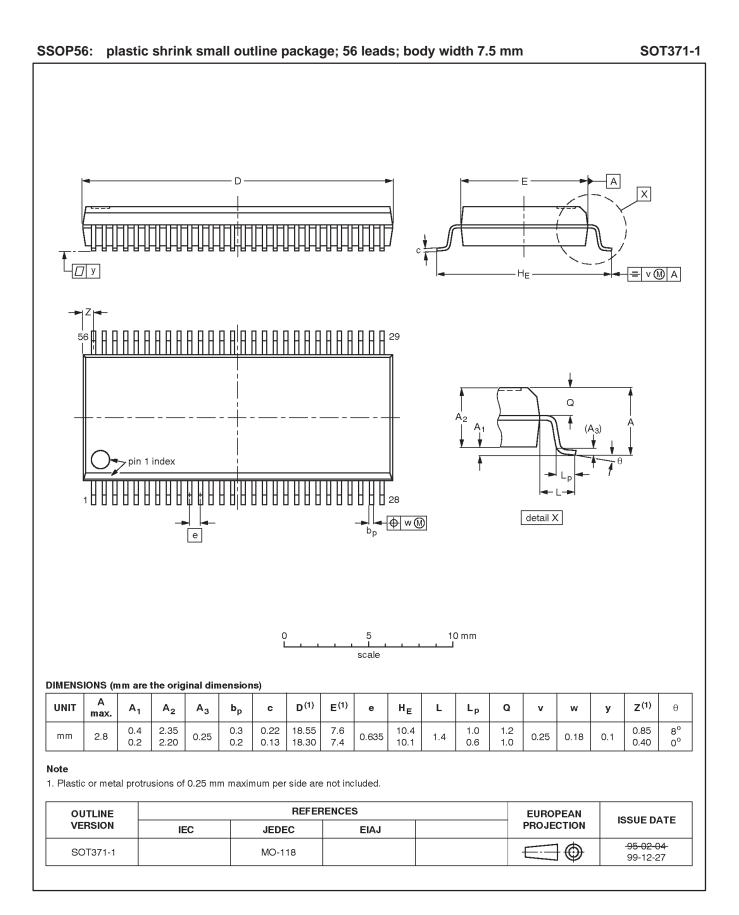


DEFINITIONS

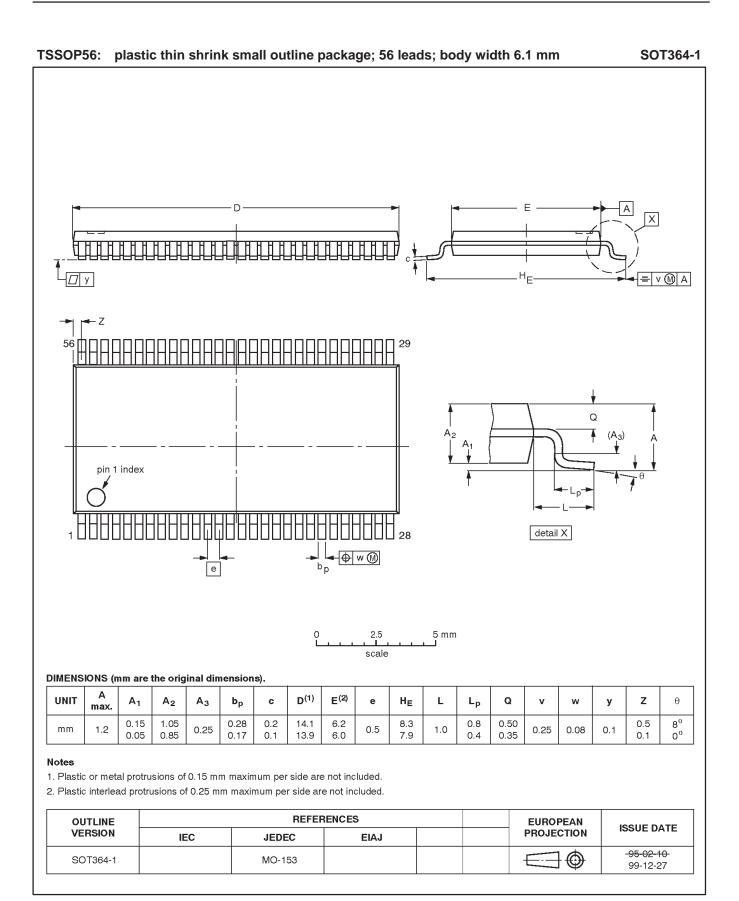
- R_L = Load resistor; see AC CHARACTERISTICS for value.
- $\label{eq:CL} \begin{array}{ll} \mathsf{C}_{\mathsf{L}} = & \mathsf{Load} \mbox{ capacitance includes jig and probe capacitance;} \\ & \mathsf{see} \mbox{ AC CHARACTERISTICS for value.} \end{array}$
- $\label{eq:RT} \mathsf{R}_\mathsf{T} = \quad \text{Termination resistance should be equal to } \mathsf{Z}_\mathsf{OUT} \text{ of } \\ \text{pulse generators.}$

Amplitude Rep. Rate t _W t _R t _F	FAMILY	IN	INPUT PULSE REQUIREMENTS				
	FAMILI	Amplitude	Rep. Rate	t _W	t _R	t _F	
74AB1/H16 3.0V 1MHZ 500ns 2.5ns 2.5ns	74ABT/H16	3.0V	1MHz	500ns	2.5ns	2.5ns	

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REVISION HISTORY

Rev	Date	Description
_2	20021217	Product data (9397 750 10858); ECN 853-1824 29295 of 12 December 2002. Supersedes data of 27 February 1998 (9397 750 03504).
		Modifications:
		• Ordering information table: remove "North America" column; remove 74ABTH16827ADL package offering.
_1	19980227	Product specification (9397 750 03504). ECN 853-1824 19025 of 27 February 1998.

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Data sheet status

	1		
Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

Definitions

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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